



SOT841-4

plastic thermal enhanced thin quad flat package; 80 leads;
body 12 x 12 x 1 mm; exposed die pad

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HTQFP80
Package type industry code	HTQFP80
Package style descriptive code	HTQFP (thermal enhanced thin quad flat package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MS-026
Mounting method type	S (surface mount)
Issue date	20-6-2006

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		11.9	-	12	12.1	mm
E	package width		11.9	-	12	12.1	mm
A	seated height		[tbd]	-	1.2	1.2	mm
A ₂	package height		0.95	-	1	1.05	mm
n ₂	actual quantity of termination		-	-	80	-	



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2. Package outline

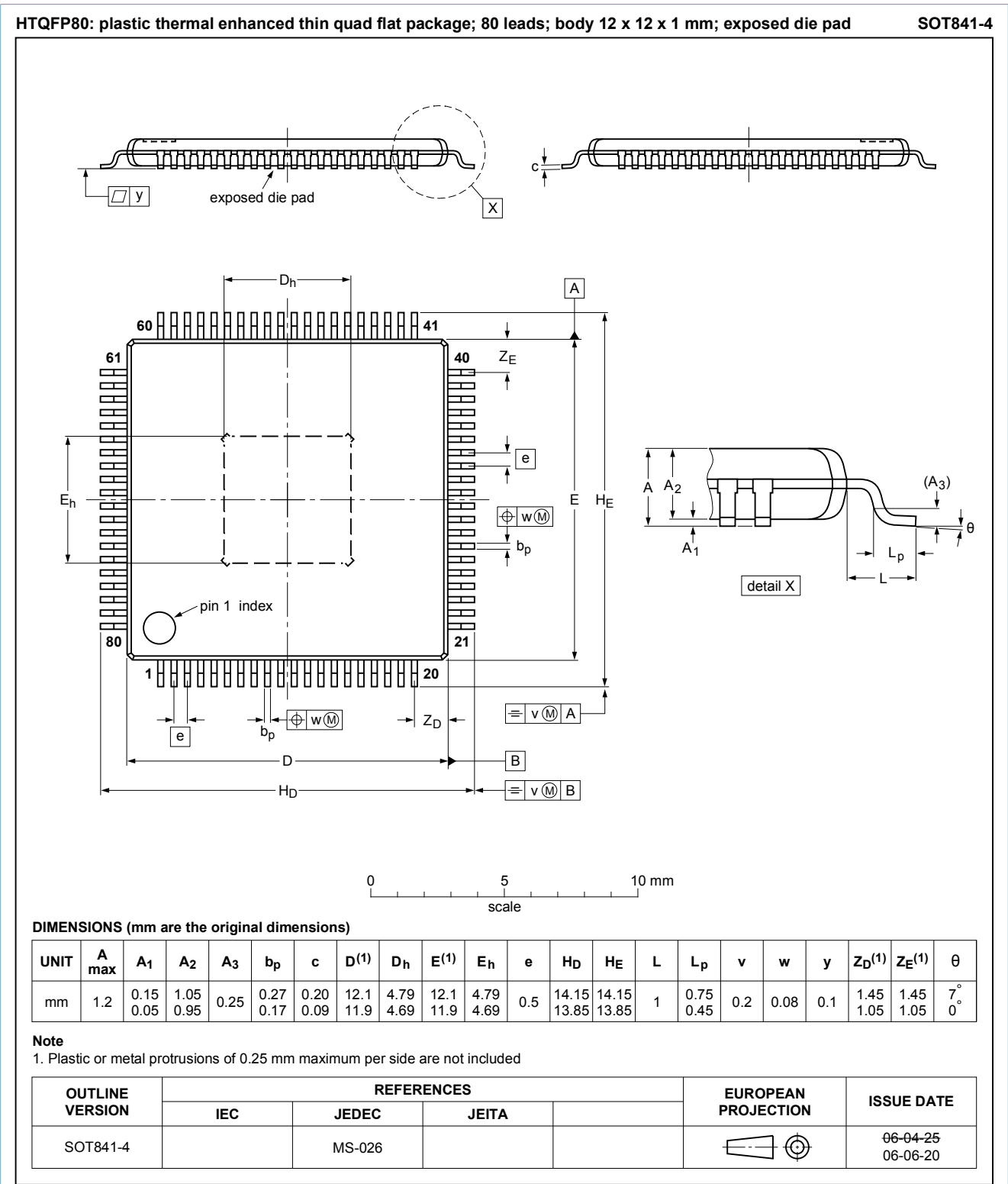


Fig. 1. Package outline HTQFP80 (SOT841-4)

3. Soldering

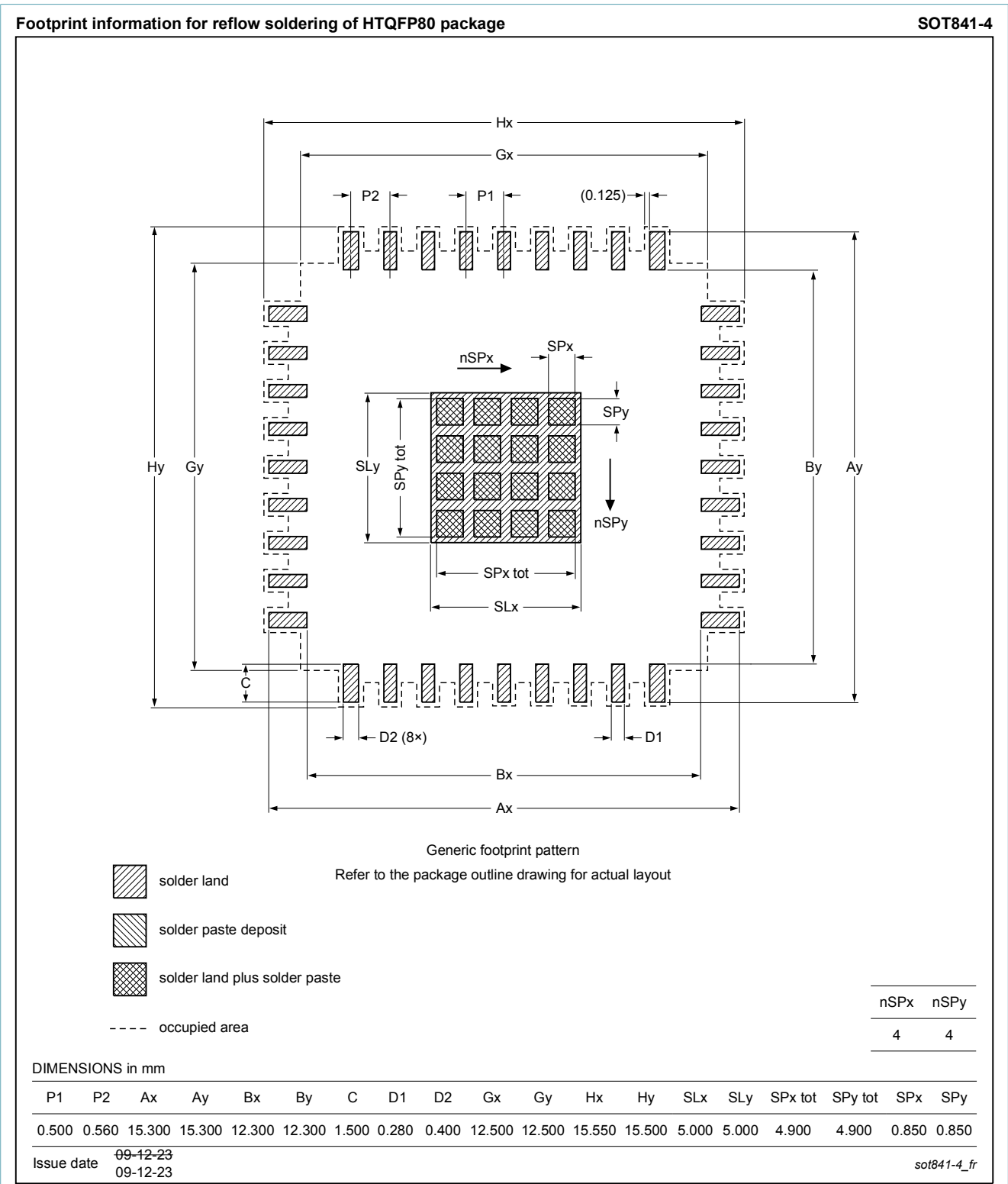


Fig. 2. Reflow soldering footprint for HTQFP80 (SOT841-4)

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4. Legal information

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